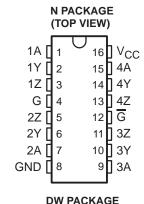
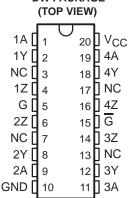
- Meets or Exceeds the Requirements of ANSI Standards EIA/TIA-422-B and RS-485 and ITU Recommendation V.11
- Designed for Multipoint Transmission on Long Bus Lines in Noisy Environments
- 3-State Outputs
- Common-Mode Output Voltage Range of –7 V to 12 V
- Active-High and Active-Low Enables
- Thermal Shutdown Protection
- Positive- and Negative-Current Limiting
- Operates From Single 5-V Supply
- Logically Interchangeable With AM26LS31

## description

The SN75172 is a monolithic quadruple differential line driver with 3-state outputs. It is designed to meet the requirements of ANSI Standards EIA/TIA-422-B and RS-485 and ITU Recommendation V.11. The device is optimized for balanced multipoint bus transmission at rates of up to 4 megabaud. Each driver features wide positive and negative common-mode output voltage ranges, making it suitable for party-line applications in noisy environments.





NC - No internal connection

The SN75172 provides positive- and negative-current limiting and thermal shutdown for protection from line fault conditions on the transmission bus line. Shutdown occurs at a junction temperature of approximately 150°C. This device offers optimum performance when used with the SN75173 or SN75175 quadruple differential line receivers.

The SN75172 is characterized for operation from 0°C to 70°C.

# FUNCTION TABLE (each driver)

INPUT	ENAI	BLES	OUTPUTS			
Α	G	G	Υ	Z		
Н	Н	Х	Н	L		
L	Н	X	L	Н		
Н	Х	L	Н	L		
L	Х	L	L	Н		
Х	L	Н	Z	Z		

H = high level, L = low level, X = irrelevant,

Z = high impedance (off)



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

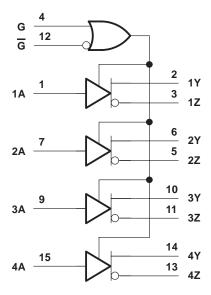


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# logic symbol†

#### G ΕN 12 2 **1Y** $\nabla$ 3 1Z $\nabla$ 6 2Y 5 2Z 10 **3Y** 11 3Z 14 4Y 15 13 4Z

### logic diagram (positive logic)



# absolute maximum ratings over operating free-air temperature (unless otherwise noted)‡

Supply voltage, V <sub>CC</sub> (see Note 1)	
Voltage range at any bus terminal	–10 V to 15 V
Input voltage, V <sub>I</sub>	5.5 V
Continuous total dissipation	See Dissipation Rating Table
Operating free-air temperature range, T <sub>A</sub>	0°C to 70°C
Storage temperature range, T <sub>stq</sub>	65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

<sup>‡</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to the network ground terminal.

#### **DISSIPATION RATING TABLE**

PACKAGE	$T_{\mbox{$\Delta$}} \leq 25^{\circ}\mbox{$C$}$ POWER RATING	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 70°C POWER RATING
DW	1125 mW	9.0 mW/°C	720 mW
N	1150 mW	9.2 mW/°C	736 mW

<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Terminal numbers shown are for the N package.

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# recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>	4.75	5	5.25	V
High-level input voltage, VIH	2			V
Low-level input voltage, V <sub>IL</sub>			0.8	V
Common-mode output voltage, V <sub>OC</sub>		-	7 to 12	V
High-level output current, I <sub>OH</sub>			-60	mA
Low-level output current, IOL			60	mA
Operating free-air temperature, T <sub>A</sub>	0		70	°C

# electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

	PARAMETER		TEST CONDITIONS	3	MIN	TYP <sup>†</sup>	MAX	UNIT
VIK	Input clamp voltage	$I_{I} = -18 \text{ mA}$					-1.5	V
٧o	Output voltage	IO = 0			0		6	V
Vон	High-level output voltage	V <sub>IH</sub> = 2 V,	V <sub>IL</sub> = 0.8 V,	$I_{OH} = -33 \text{ mA}$		3.7		V
VOL	Low-level output voltage	V <sub>IH</sub> = 2 V,	V <sub>IL</sub> = 0.8 V,	I <sub>OH</sub> = 33 mA		1.1		V
V <sub>OD1</sub>	Differential output voltage	I <sub>O</sub> = 0			1.5		6	V
V <sub>OD2</sub>	Differential output voltage	R <sub>L</sub> = 100 Ω,	See Figure 1		1/2 V <sub>OD1</sub> or 2 <sup>‡</sup>			V
		$R_L = 54 \Omega$ ,	See Figure 1		1.5	2.5	5	V
V <sub>OD3</sub>	Differential output voltage	See Note 2			1.5		5	V
Δ V <sub>OD</sub>	Change in magnitude of differential output voltage§						±0.2	V
Voc	Common-mode output voltage¶	$R_L = 54 \Omega \text{ or } $	100 Ω,	See Figure 1			+3 -1	V
Δ Vocl	Change in magnitude of common-mode output voltage§						±0.2	V
IO	Output current with power off	$V_{CC} = 0$ ,	$V_0 = -7 \text{ V to } 12 \text{ V}$				±100	μΑ
loz	High-impedance-state output current	$V_O = -7 \text{ V to}$	12 V				±100	μΑ
lіН	High-level input current	V <sub>I</sub> = 2.7 V					20	μΑ
I <sub>I</sub> L	Low-level input current	V <sub>I</sub> = 0.5 V					-360	μΑ
		$V_0 = -7 V$					-180	
los	Short-circuit output current	AO = ACC					180	mA
		V <sub>O</sub> = 12 V					500	
loo	Supply current (all drivers)	No load	Outputs enabled			38	60	mA
Icc	Cupply culterit (all univers)	140 load	Outputs disabled			18	40	

NOTE 2: See Figure 3-5 of EIA Standard RS-485.



<sup>†</sup> All typical values are at  $V_{CC}$  = 5 V and  $T_A$  = 25°C. ‡ The minimum  $V_{OD2}$  with a 100- $\Omega$  load is either 1/2  $V_{OD1}$  or 2 V, whichever is greater. §  $\Delta |V_{OD}|$  and  $\Delta |V_{OC}|$  are the changes in magnitude of  $V_{OD}$  and  $V_{OC}$ , respectively, that occur when the input is changed from a high level to a low level.

<sup>¶</sup> In ANSI Standard EIA/TIA-422-B, VOC, which is the average of the two output voltages with respect to ground, is called output offset voltage, Vos.

SYM	ROI	FOL	ΙΙνΔΙ	_ENTS

DATA SHEET PARAMETER	EIA/TIA-422-B	RS-485
Vo	V <sub>oa</sub> , V <sub>ob</sub>	V <sub>oa</sub> , V <sub>ob</sub>
IV <sub>OD1</sub> I	V <sub>o</sub>	Vo
IV <sub>OD2</sub> I	$V_t (R_L = 100 \Omega)$	$V_t (R_L = 54 \Omega)$
IV <sub>OD2</sub> I		V <sub>t</sub> (Test Termination) Measurement 2)
Δ V <sub>OD</sub>	$  V_t  -  \overline{V}_t  $	$    V_t   -   \overline{V}_t    $
Voc	V <sub>os</sub>	V <sub>os</sub>
Δ V <sub>OC</sub>	$ V_{OS} - \overline{V}_{OS} $	$ V_{OS} - \overline{V}_{OS} $
los	I <sub>sa</sub>  , I <sub>sb</sub>	
lo	$ I_{xa} , I_{xb} $	l <sub>ia</sub> ,l <sub>ib</sub>

# switching characteristics, $V_{CC}$ = 5 V, $T_A$ = 25°C

	PARAMETER	TEST CON	MIN	TYP	MAX	UNIT	
td(OD)	Differential-output delay time	$R_1 = 54 \Omega$	Soo Eiguro 2		45	65	ns
t <sub>t</sub> (OD)	Differential-output transition time	KL = 54 52,	See Figure 2		80	120	ns
<sup>t</sup> PZH	Output enable time to high level	$R_L = 110 \Omega$ ,	See Figure 3		80	120	ns
tpzL	Output enable time to low level	$R_L = 110 \Omega$ ,	See Figure 4		45	80	ns
tPHZ	Output disable time from high level	$R_L = 110 \Omega$ ,	See Figure 3		78	115	ns
tPLZ	Output disable time from low level	$R_L = 110 \Omega$ ,	See Figure 4		18	30	ns

### PARAMETER MEASUREMENT INFORMATION

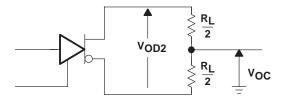
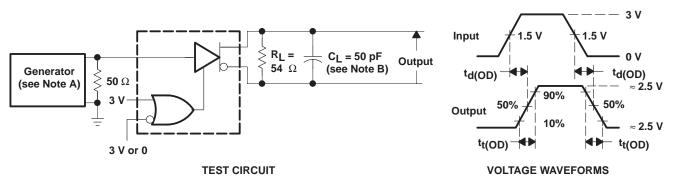


Figure 1. Differential and Common-Mode Output Voltages



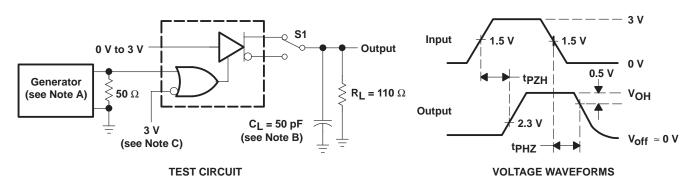
NOTES: A. The input pulse is supplied by a generator having the following characteristics:  $t_f \le 5$  ns,  $t_f \le 5$ 

B.  $C_L$  includes probe and stray capacitance.

Figure 2. Differential-Output Test Circuit and Voltage Waveforms

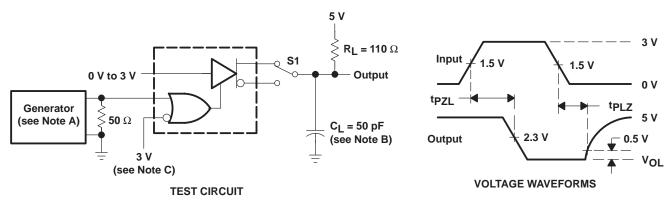


#### PARAMETER MEASUREMENT INFORMATION



- NOTES. A. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  1 MHz, duty cycle = 50%,  $t_{\Gamma} \leq$  5 ns,  $t_{f} \leq$  5 ns,  $Z_{O} =$  50  $\Omega$ .
  - B. C<sub>L</sub> includes probe and stray <u>capacitance</u>.
  - C. To test the active-low enable  $\overline{G}$ , ground G and apply an inverted waveform to  $\overline{G}$ .

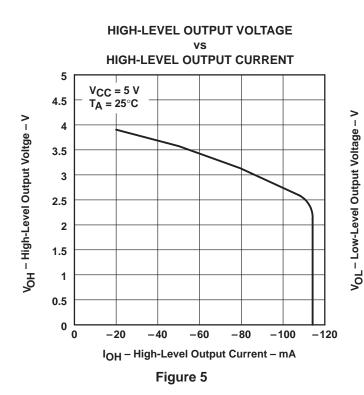
Figure 3. Test Circuit and Voltage Waveforms

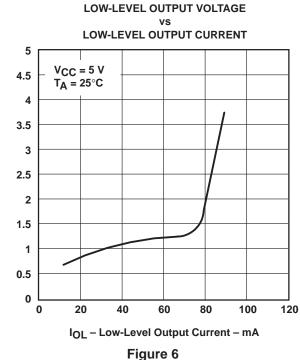


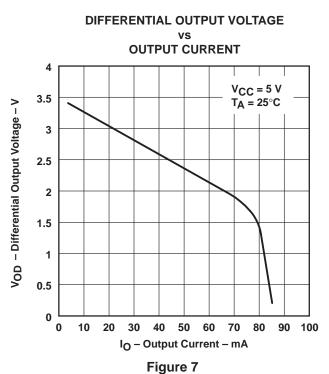
- NOTES. A. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  1 MHz, duty cycle = 50%,  $t_f \leq$  5 ns,  $t_f \leq$  6 ns,  $t_f \leq$  6 ns,  $t_f \leq$  7 ns,  $t_f \leq$  7 ns,  $t_f \leq$  8 ns,  $t_f \leq$  9 ns,  $t_$ 
  - B. C<sub>L</sub> includes probe and stray capacitance.
  - C. To test the active-low enable  $\overline{G}$ , ground G and apply an inverted waveform to  $\overline{G}$ .

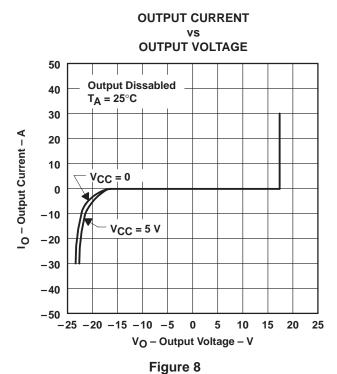
Figure 4. Test Circuit and Voltage Waveforms

#### TYPICAL CHARACTERISTICS

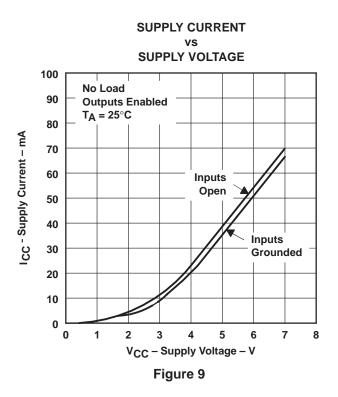


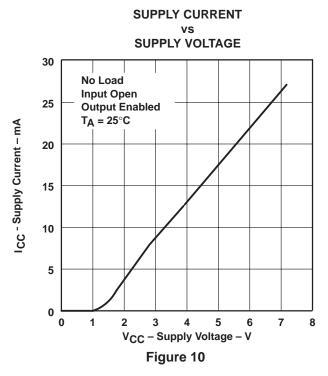




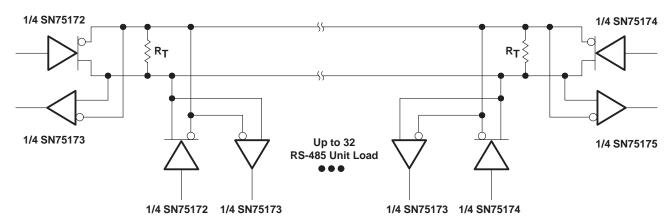


#### TYPICAL CHARACTERISTICS





### **APPLICATION INFORMATION**



NOTE A: The line length should be terminated at both ends in its characteristic impedance (R<sub>T</sub> = Z<sub>O</sub>). Stub lengths off the main line should be kept as short as possible.

Figure 11

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#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
SN75172DW	LIFEBUY	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75172	
SN75172DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75172	Samples
SN75172N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN75172N	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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# **PACKAGE OPTION ADDENDUM**

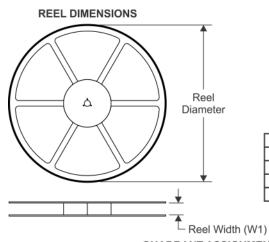
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# **PACKAGE MATERIALS INFORMATION**

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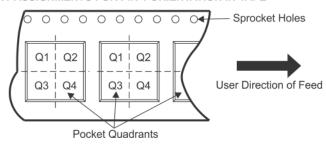
# TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

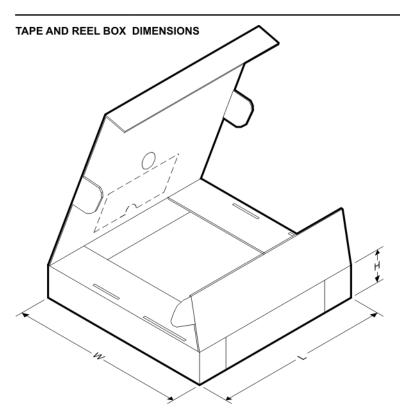
# QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75172DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

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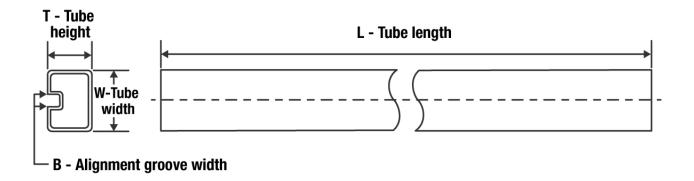
#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75172DWR	SOIC	DW	20	2000	367.0	367.0	45.0

# PACKAGE MATERIALS INFORMATION

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### **TUBE**



#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN75172DW	DW	SOIC	20	25	507	12.83	5080	6.6
SN75172DW	DW	SOIC	20	25	506.98	12.7	4826	6.6
SN75172N	N	PDIP	16	25	506	13.97	11230	4.32

# N (R-PDIP-T\*\*)

# PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



#### NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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